## **IoT SuperServer SYS-211SE-31AS**



## More details he

## **Key Applications**

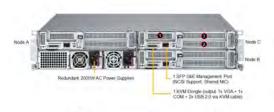
Multi-Access Edge Computing, Flex-RAN, Open-RAN vBBU, Telecom DRAN, CRAN, and Edge Core Application, Enterprise Edge Computing,

## **Key Features**

- Single Socket E (LGA-4189) 4th Gen Intel® Xeon® Scalable processor (per node);
- 8 DIMMs; Up to 2TB 3DS ECC DDR5-4800: RDIMM/LRDIMM (per node);
- 2 PCle Gen5 x16 FHHL slot and 1 PCle Gen5 x16 HHHL slot (per node);
- 2 NVMe M.2 2280/22110 (per node);
- 4 counter-rotated fan speed control (per node); 1 Air Shroud (per node);
- Front-access 2000W AC Redundant Power Supplies (per system);

Form Factor	2U Rackmount
	Enclosure: 449 x 88 x 430mm (17.7" x 3.5" x 16.9")
	Package: 750 x 240 x 590mm (29.5" x 9.5" x 23.2")
Processor	4th Gen Intel® Xeon® Scalable processors
	Single Socket LGA-4677 (Socket E) supported
	(CPUs (air cooled) with TDP over 205W are only supported under specific conditions. Contact customer support
	for details., Supports 85W - 300W TDP CPUs (Aircooled))
System Memory	8 DIMM slots
	Up to 2TB ECC RDIMM/LRDIMM, DDR5-4800MHz
Drive Bays	2 M.2 NVMe
	M-Key, 2280/22110
Expansion Slots	1 PCIe 5.0 x16 LP slot(s)
	2 PCIe 5.0 x16 FHHL slot(s)
On-Board Devices	Chipset: Intel® C741
	Network Connectivity: 1x 1GbE SFP
	IPMI: Support for Intelligent Platform Management Interface v.2.0
	IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
Input / Output	LAN: 1 SFP GbE LAN port (Shared NIC, IPMI)
	Video: 1 VGA port(s)
	Serial Port: 1 COM Port(s) (1 COM COM port through KVM cable (from KVM dongle))

ort View - System)





Stot (Sinde A-C)	Description
0	POw 55 xXX (LP) stat
0	POe 5 0 x15 (FHHL) slot
0	PCW 5 0 X15 (FIRE) stat.

System Cooling 4 heavy duty fan(s)

4 heavy duty fan(s)

Power Supply 2000W Redundant AC 100-240V Power Supply

Dimension (W x H x L): 73.5 x 40 x 265 mm

Management IPMI 2.0; SuperDoctor® 5

PC Health Monitoring CPU: Monitors for CPU Cores, Chipset Voltages, Memory

FAN: Fans with tachometer monitoring Status monitor for speed control

Pulse Width Modulated (PWM) fan connectors

Temperature: Monitoring for CPU and chassis environment

CPU thermal trip support, PEPI

Dimensions and Weight Height: 3.5" (88 mm)

Width: 17.7" (449 mm)
Depth: 16.9" (430 mm)
Gross Weight: 70.6 lbs (32 kg)
Net Weight: 55.1 lbs (25 kg)

Packaging: 9.5" (H) x 29.5" (W) x 23.2" (D)

Available Color: Silver

Operating Environment Operating Temperature: 0°C ~ 35°C (32°F ~ 95°F)

Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)

Motherboard Super X13SEED-SF

Chassis CSE-SE201-R2K07P